

Title (en)

ELECTRODEPOSITION BATHS, SYSTEMS AND METHODS

Title (de)

BÄDER, SYSTEME UND VERFAHREN ZUR ELEKTROTAUHLACKIERUNG

Title (fr)

BAINS, SYSTÈMES ET PROCÉDÉS DE DÉPÔT ÉLECTROLYTIQUE

Publication

EP 2356267 A1 20110817 (EN)

Application

EP 09825108 A 20091104

Priority

- US 2009005967 W 20091104
- US 26697908 A 20081107
- US 26701008 A 20081107

Abstract (en)

[origin: WO2010053540A1] Electrodeposition baths, systems and methods are provided. In some embodiments, the baths, systems and methods are used to deposit metal alloy coatings.

IPC 8 full level

C25D 3/56 (2006.01); **B22F 7/00** (2006.01); **B22F 7/04** (2006.01); **C25D 5/18** (2006.01); **C25D 21/12** (2006.01); **C25D 3/66** (2006.01); **G01N 27/42** (2006.01)

CPC (source: EP KR US)

B22F 7/04 (2013.01 - EP); **C25D 3/12** (2013.01 - KR); **C25D 3/56** (2013.01 - EP KR US); **C25D 3/562** (2013.01 - EP); **C25D 5/18** (2013.01 - EP KR US); **C25D 5/611** (2020.08 - EP KR US); **C25D 5/617** (2020.08 - EP KR US); **C25D 5/619** (2020.08 - EP KR US); **C25D 5/627** (2020.08 - EP KR US); **C25D 21/12** (2013.01 - EP); **B22F 2998/00** (2013.01 - EP); **C25D 3/66** (2013.01 - EP); **G01N 27/42** (2013.01 - EP)

C-Set (source: EP)

B22F 2998/00 + **C22C 1/045**

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO SE SI SK SM TR

DOCDB simple family (publication)

WO 2010053540 A1 20100514; CA 2742934 A1 20100514; CN 102272356 A 20111207; EP 2356267 A1 20110817; EP 2356267 A4 20160330; JP 2012508322 A 20120405; JP 2015165053 A 20150917; KR 20110083707 A 20110720

DOCDB simple family (application)

US 2009005967 W 20091104; CA 2742934 A 20091104; CN 200980153812 A 20091104; EP 09825108 A 20091104; JP 2011535556 A 20091104; JP 2015098516 A 20150513; KR 20117012744 A 20091104